

REMARKS:

The Office Action dated October 18, 2006 has been carefully considered.

Claims 1-6 are pending in the application. Applicants confirm that Group I claims 1-3 are withdrawn from further consideration based on a provisional election made on August 16, 2006 without traverse to prosecute the invention of Group II, claims 4-6. The Group I claims 1-3 have been cancelled.

The Office Action is based on the merits of Group II claims 4-6, inclusively.

The Examiner has rejected claims 4-6 under 35 U.S.C § 112, second paragraph, as being indefinite. In response thereto, claims 4-6 have been amended in a manner which is believed to put the claims in condition for allowance. Reconsideration and withdrawal of the rejection under § 112, second paragraph are respectfully requested.

The Examiner has also rejected the claims under 35 U.S.C. § 103(a) as being obvious over Japanese Patent Publication No. 10-022639 to *Teiichi et al.* In response thereto, Applicants state that the *Teiichi et al.* patent publication relates to a manufacturing method of a plastic flow sheet for a multilayer printed wiring board and printed board using the sheet. Furthermore, the *Teiichi et al.* disclosure aims at controlling ooze (exudation) of an insulating adhesive into through holes, which are used as Interstitial Via Holes (IVH). See provided English translation of the *Teiichi et al.* specification sections [0006] and [0031].

Furthermore, *Teiichi et al.* is an invention characterized by protecting through holes with a crosslinkable resin of the above-mentioned plastic flow sheet so that the adhesive agent does not flow into the through holes when performing heat pressing for lamination of the board, which has drilled through holes in a metallic foil affixed with an adhesive agent (3) (FIG. 1) or a laminated board affixed with an adhesive agent (31) (FIG. 2). After substrate lamination, the crosslinkable resin is also completely removed by exfoliating the plastic flow

sheet. Then, the inner wall of these through holes is metallized. Metallization is carried out by filling and the like of the through holes with electrolysis plating, or electrolytic plating and conductive paste. See provided English translation of *Teiichi et al.* FIG. 1 and FIG. 2 elements and specification sections [0007-0010] and [0019-0021].

In contrast, Applicants' present invention is characterized in that "metallic foil is bonded (laminated) on one side of a sheet-like support substrate, the metallic foil is patterned and metal conductor pieces are used for via holes". In that manner, the via holes can be formed without being filled with conductive paste or electrolytic plating. Also, superior quality via holes can be formed without containing defective shapes, such as raised or indented end faces.

For those reasons, it is respectfully submitted that the amended claims 4-6 would not have been obvious under 35 U.S.C. § 103(a) over the cited prior art to one of ordinary skill in the art. Reconsideration and withdrawal of the rejection under 35 U.S.C. § 103(a) are respectfully requested.

In view of the foregoing, entry of this Amendment and allowance of the claims are respectfully solicited.